

Title (en)

COOLING ARRANGEMENT FOR AN ELECTRONIC COMPONENT

Title (de)

KÜHLANORDNUNG FÜR EINE ELEKTRONISCHE KOMPONENTE

Title (fr)

DISPOSITIF DE REFROIDISSEMENT POUR UN COMPOSANT ÉLECTRONIQUE

Publication

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Application

EP 16766262 A 20160907

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Abstract (en)

[origin: WO2017050570A1] The invention relates to a cooling arrangement for an electronic component (11) or an electrical assembly having such a cooling arrangement. Said cooling arrangement has a passive heat sink (13) for cooling an electrical device (11). According to the invention, there is additionally provision for transducers (14), e.g. thermoelectric generators, to cause an additional cooling effect by dissipating heat from the electronic device (11) and at the same time to allow the generation of power. This can be used, by way of example, to drive an active cooling apparatus (23), such as a piezo fan (38), which additionally caters for cooling the heat sink (13) and hence improves the cooling effect. The overall system is self-sufficient in terms of energy, since the requisite power supply is obtained from the waste heat from the electronic device (11). Advantageously, the power obtained can also be made available to other functional elements. The added costs of the additional cooling are therefore compensated for by saving on an energy source.

IPC 8 full level

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